

ABSTRACT

It is an object of the present invention to provide a production process capable of precisely producing a plated shaped article of a large thickness such as a bump or a wiring, a positive radiation-sensitive resin composition which is preferably used for the process and has excellent sensitivity and resolution, and a transfer film using the composition. The above object is achieved by a positive radiation-sensitive resin composition comprising (A) a polymer containing structural units represented by the following formula (1) and/or the following formula (2) and an acid-dissociable functional group (b), (B) a component which generates an acid by irradiation with radiation and (C) an organic solvent, and is achieved by producing a positive radiation-sensitive resin film using the composition.



